AD162C Datasheet

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Version：1.2

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AD162C Features

CPU

- 32bit DSP
- Maximum speed 160MHz
- Interrupts with 8 priority level

Memory

- OTP
- Optional built-in flash memory

Clocks

- On-chip 16 MHz clock
- On-chip 200KHz lower-temperature-drift clock
- 32.768 KHz crystal oscillator

DSP Audio Processing

- Support MP2, MP3, WMA, WAV decoding
- Multi-band DRC limiter
- Multi-band EQ configuration for voice Effects

Audio Codec

- Two channels 16-bit DAC, single-ended with SNR ≥ 93dB, differential with SNR ≥ 100dB
- One channel 24-bit ADC,SNR ≥ 85dB
- Audio DAC Sampling rates of 8KHz/11.025KHz/16KHz/22.05KHz/24KHz/ 32KHz/44.1KHz/48KHz/64KHz/88.2KHz/ 96KHz are supported
- Audio ADC Sampling rates of 8KHz/11.025KHz/16KHz/22.05KHz/24KHz/ 32KHz/44.1KHz/48KHz are supported
- Audio DAC support single-ended and differential cap-less mode
- Support analog audio input
- Support for driving 16 or 32 ohm speaker

Peripherals

- One full speed USB OTG controller
- One SD host controller for MMC/SD
- Three multi-function 32-bit timers, support capture and PWM mode
- UART0 controller
- The UART1 supports DMA and flow control
- One IIC Master controller
- Two SPI Master / Slaver controller with DMA
- One QDEC interface
- 7-channel 10-bit general purpose ADC
- 4-channel Advance PWM controller
- 9 Individually programmable and multiplexed GPIO pins
- Digital peripheral crossbar
- Up to 9 external interrupt / wake-up source (low power available,can be multiplexed to any I/O)

PMU

- Built-in lithium battery charging manager,up to 120mA charging current
- RTC Alarm Wakeup
- Less than 2uA soft off current
- VPWR range : 4.5V to 6.0V
- VBAT range : 2.2V to 5.0V
- IOVDD range : 2.1V to 3.6V

Packages

- SOP16

Temperature

- Operating temperature: -40℃ to +85℃
- Storage temperature: -65℃ to +150℃

Applications

- Audio player
- Microcontrollers

1 Block Diagram

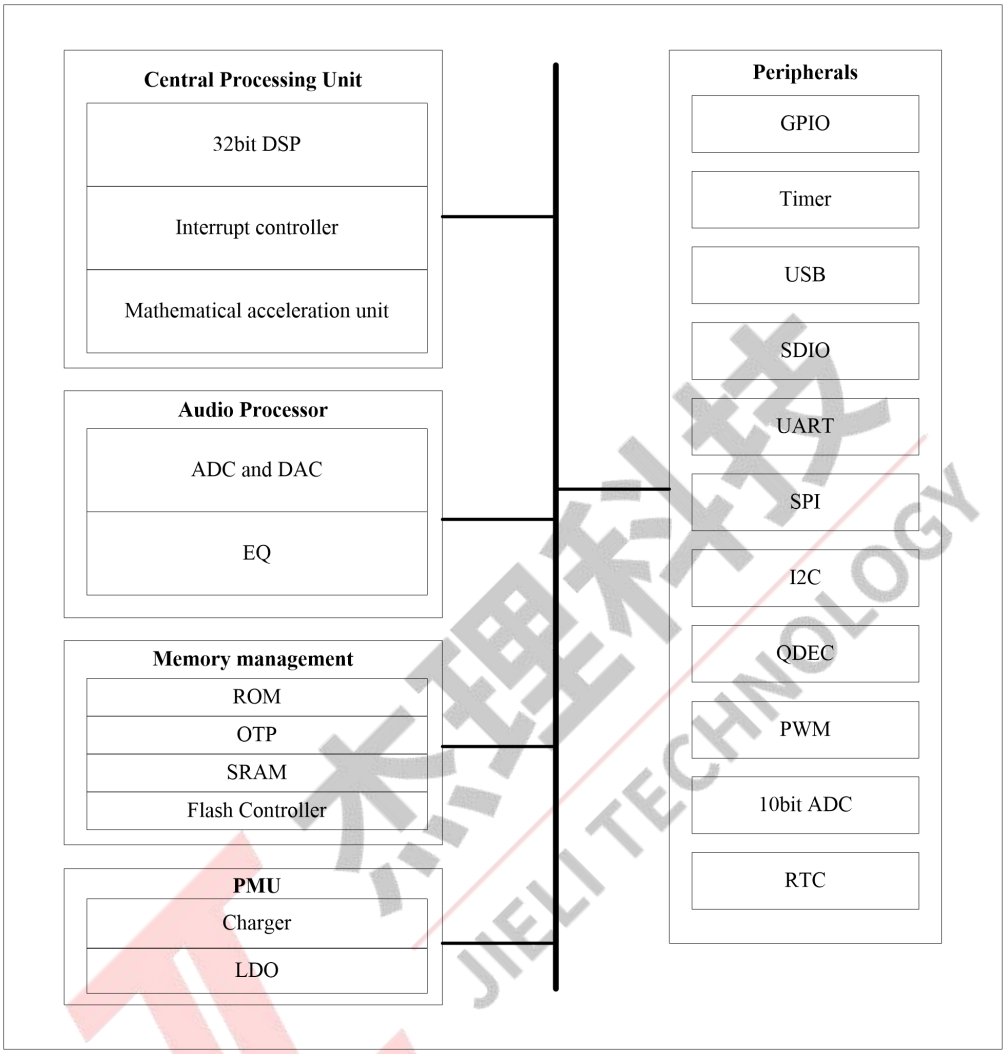


Figure 1-1 AD162C Block Diagram

2 Pin Definition

2.1 Pin Assignment

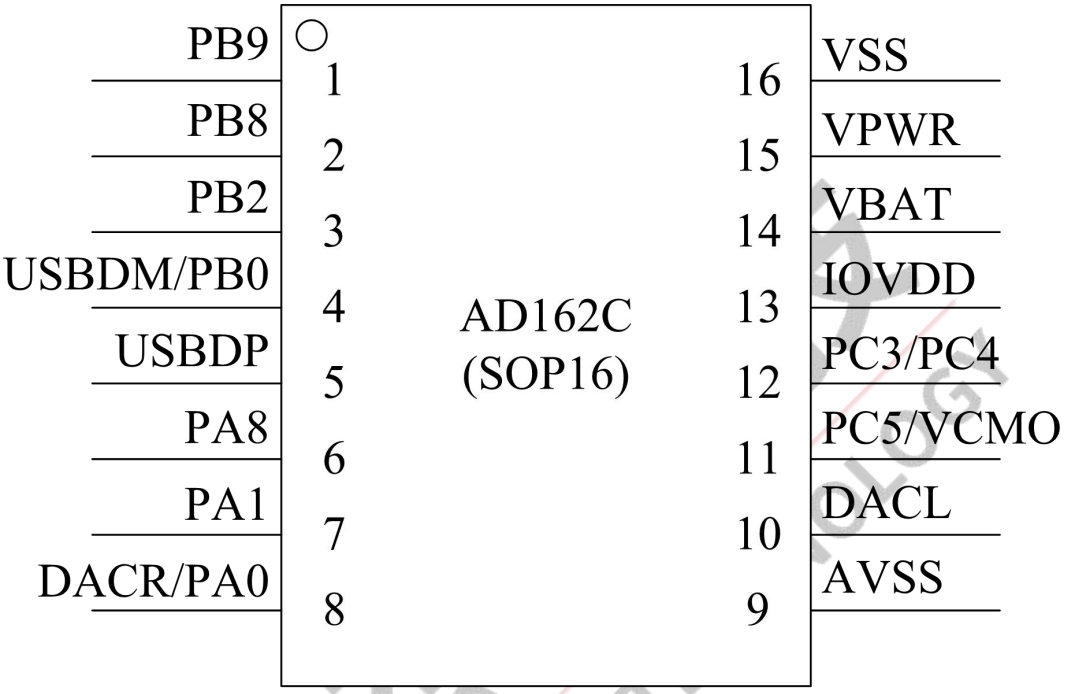


Figure 2-1 AD162C Package Diagram

2.2 Pin Description

Table 2-1 AD162C Pin Description

PIN NO.	Name	Type	Function	Other Function
1	PB9	I/O	GPIO	ROSCI_32K:32.768KHz crystal oscillator input; CLKOUT2:Clock Out2;
2	PB8	I/O	GPIO	ROSCO_32K:32.768KHz crystal oscillator output; ADC10:ADC Input Channel 10; CLKOUT1:Clock Out1;
3	PB2	I/O	GPIO	ADC6:ADC Input Channel 6;
4	PB0	I/O	GPIO	ADC5:ADC Input Channel 5;
	UDBDM	I/O	USB Negative Data (pull down)	SPI1DO(A):SPI1 Data Out(A); IIC0_SDA(A):IIC0 SDA(A); UART0RXA:Uart0 Data Input(A); ADC15:ADC Input Channel 15;
5	USBDP	I/O	USB Positive Data (pull down)	SPI1CLKA:SPI1 Clk(A); IIC0_SCL(A):IIC0 SCL(A); UART0TXA:Uart0 Data Output(A); ADC14:ADC Input Channel 14;
6	PA8	I/O	GPIO (pull up)	Long press reset; ADC3:ADC Input Channel 3;
7	PA1	I/O	GPIO	MICIN0:MIC0 Input Channe; UART1RXB:Uart1 Data Input(B); TMR0:Timer0 Clock Input;
8	PA0	I/O	GPIO	MICLDO:Microphone linear voltage regulator output; ADC0:ADC Input Channel 0; UART1TXB:Uart1 Data Output(B); PWM0:Timer0 PWM Output;
	DACR	AO		Right channel audio output;
9	AVSS	G		Audio ground;
10	DACL	AO		Left channel audio output;
11	VCMO	AO		negative of earphone;
	PC5	I/O	GPIO	AINR:Right channel analog audio input;
12	PC4	I/O	GPIO	AINL:Left channel analog audio input; TMR2:Timer2 Clock Input;
	PC3	I/O	GPIO	SDPG:SD card Power Gate; ADC13:ADC Input Channel 13;
13	IOVDD	PO	Power supply for GPIO	Built-in linear voltage regulator output;
14	VBAT	P		Battery interface;

15	VPWR (PP0)	PI (I/O)	GPIO	Charge Power Input; UART1TXA:Uart1 Data Output(A); UART1RXA:Uart1 Data Input(A); CAP1:Timer1 Capture;
16	VSS	G		System ground;

Pin Type	**Description**	**Pin Type**	**Description**
P	Power	I/O	Input or Output
PI	Power Input	I	Input
PO	Power Output	O	Output
AO	Analog Output	G	Ground

3 Electrical Characteristics

3.1 Absolute Maximum Ratings

Table 3-1

Symbol	Parameter	Min	Max	Unit
Topt	Operating temperature	-40	+85	°C
Tstg	Storage temperature	-65	+150	°C
VBAT	Supply Voltage	-0.3	5.0	V
VPWR	Charger Voltage	-0.3	6.0	V
V_{IOVDD}	Voltage applied at IOVDD	-0.3	3.6	V
V_{GPIO}	Voltage applied to GPIO	-0.3	IOVDD+0.3	V

Note : The chip can be damaged by any stress in excess of the absolute maximum ratings listed below

3.2 PMU Characteristics

Table 3-2

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
VBAT	Voltage Input	2.2	3.7	5.0	V	_
VPWR	Charger supply Voltage	4.5	5.0	6.0	V	_
IOVDD	Voltage output	2.1	3.0	3.6	V	VBAT = 4.2V, 10mA loading
	Loading current	_	_	100	mA	IOVDD=3.3V@VBAT = 3.6V
V_{LVD}	Voltage input	2.1	2.8	2.8	V	Low-Voltage Detection of IOVDD

3.3 Battery Charge

Table 3-3

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{PWR}	Charge Input Voltage Range	4.5	5	6.0	V	_
$V_{BAT\ Float}$	Battery Charge Termination Voltage	4.15	4.2	4.25	V	VPWR＞4.5V
		4.30	4.35	4.40	V	VPWR＞4.65V
I_{BAT}	Fast Charge Current	20	_	120	mA	VBAT=4.0V@VPWR=5.0V
I_{END}	Charge Termination Current Threshold	2	_	12	mA	CHG_IIFULL_S==0,1
V_{Trikl}	Trickle Charge Voltage	_	3.0	_	V	VPWR＞4.5V
I_{Trikl}	Trickle Charge Current	2	_	12	mA	V_{BAT}<V_{Trikl}

3.4 IO Input/Output Electrical Logical Characteristics

Table 3-4

GPIO input characteristics						
Symbol	**Parameter**	**Min**	**Typ**	**Max**	**Unit**	**Test Conditions**
V_{IL}	Low-Level Input Voltage	-0.3	_	0.3* IOVDD	V	IOVDD = 3.0V
V_{IH}	High-Level Input Voltage	0.7* IOVDD	_	IOVDD+0.3	V	IOVDD = 3.0V
GPIO output characteristics						
Symbol	**Parameter**	**Min**	**Typ**	**Max**	**Unit**	**Test Conditions**
V_{OL}	Low-Level Output Voltage	_	_	0.1* IOVDD	V	IOVDD = 3.0V
V_{OH}	High-Level Output Voltage	0.9* IOVDD	_	_	V	IOVDD = 3.0V

3.5 Internal Resistor Characteristics

Table 3-5

Port	**Drive Current**	**Internal Pull-Up Resistor**	**Internal Pull-Down Resistor**	**Comment**
PA0,PA1,PA8 PB0,PB2 PB8,PB9 PC3~PC5	2mA(HD1,HD0==0,0) 5.6mA(HD1,HD0==0,1) 18mA(HD1,HD0==1,0) 30mA(HD1,HD0==1,1)	10K	10K	1. PA8 default pull up 2. USBDM,USBDP default pull down 3. Internal pull-up/pull-down resistance | accuracy ±20%
PP0(VPWR)	1.4mA	10K	10K	
USBDP	27mA	1.5K	15K	
USBDM		180K	15K	

3.6 Audio DAC Characteristics

Table 3-6

Parameter	**MODE**	**Min**	**Typ**	**Max**	**Unit**	**Test Conditions**
Frequency Response		20	_	20K	Hz	1KHz/0dB 10k ohm loading With A-Weighted Filter IOVDD>2.7V
Output Swing	Diff (R to L)	_	1.5	_	Vrms	
	Single-ended	_	750	_	mVrms	
THD+N	Diff (R to L)	_	-80	_	dB	
	Single-ended	_	-80	_	dB	
S/N	Diff (R to L)	_	100	_	dB	
	Single-ended	_	93	_	dB	
Dynamic Range	Diff (R to L)	_	100	_	dB	1KHz/-60dB 10k ohm loading With A-Weighted Filter IOVDD>2.7V
	Single-ended	_	93	_	dB	

Noise Floor	Diff (R to L)	_	13	_	uVrms	With A-Weighted Filter IOVDD>2.7V
	Single-ended	_	18	_	uVrms	
Crosstalk	Single-ended	_	-93	_	dB	10KHz/0dB 10k ohm loading IOVDD>2.7V
	(R and L) to VCMO	_	-60	_	dB	10KHz/0dB 32 ohm loading IOVDD>2.7V
	(R and L) to VCMO	_	-57	_	dB	10KHz/0dB 16 ohm loading IOVDD>2.7V

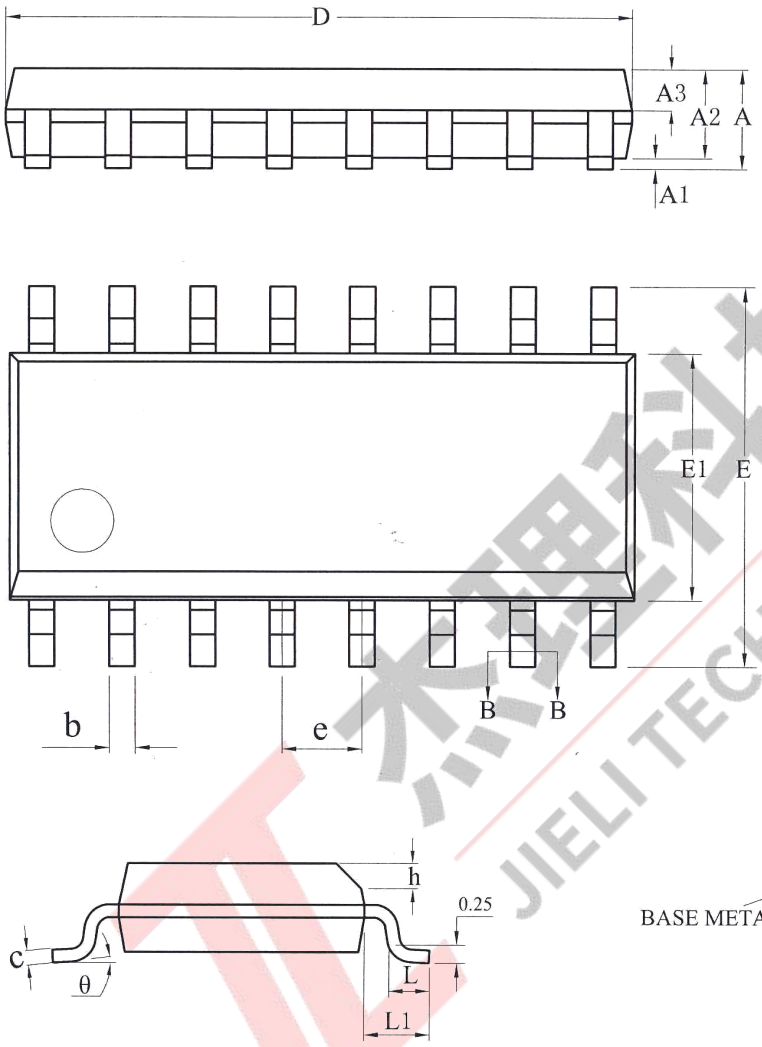
3.7 Audio ADC Characteristics

Table 3-7

Parameter	MODE	Min	Typ	Max	Unit	Test Conditions
Dynamic Range	Single-ended	_	85	_	dB	Fsample=44.1KHz,Gain=-2dB Fin=1KHz @1Vpp NO A-wt 20Hz-20KHz IOVDD>2.7V
		_	72	_	dB	Fsample=44.1KHz,Gain=14dB Fin=1KHz @160mVpp NO A-wt 20Hz-20KHz IOVDD>2.7V
S/N	Single-ended	_	85	_	dB	Fsample=44.1KHz,Gain=-2dB Fin=1KHz @1Vpp NO A-wt 20Hz-20KHz IOVDD>2.7V
		_	72	_	dB	Fsample=44.1KHz,Gain=14dB Fin=1KHz @160mVpp NO A-wt 20Hz-20KHz IOVDD>2.7V
THD+N	Single-ended	_	-78	_	dB	Fsample=44.1KHz,Gain=-2dB Fin=1KHz @1Vpp NO A-wt 20Hz-20KHz IOVDD>2.7V
		_	-70	_	dB	Fsample=44.1KHz,Gain=14dB Fin=1KHz @160mVpp NO A-wt 20Hz-20KHz IOVDD>2.7V

4 Package Information

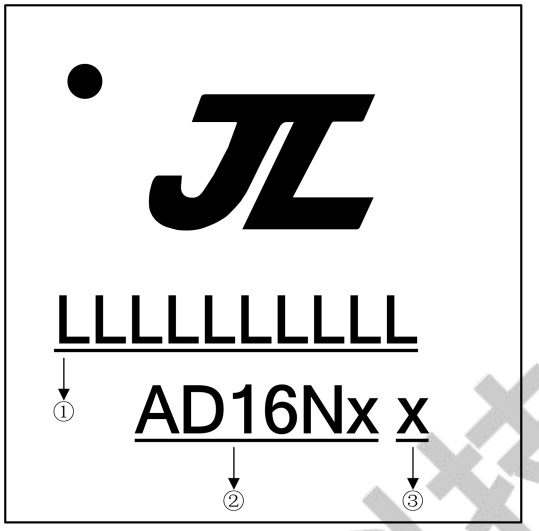
4.1 SOP16



SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.75
A1	0.10	—	0.225
A2	1.30	1.40	1.50
A3	0.60	0.65	0.70
b	0.39	—	0.47
b1	0.38	0.41	0.44
c	0.20	—	0.24
c1	0.19	0.20	0.21
D	9.80	9.90	10.00
E	5.80	6.00	6.20
E1	3.80	3.90	4.00
e	1.27BSC		
h	0.25	—	0.50
L	0.50	—	0.80
L1	1.05REF		
θ	0	—	8°

Figure 4-1 AD162C Package

5 IC Marking Information



① LLLLLLLLLL：Production Batch
② AD16Nx：Chip Model
③ Built-in flash size
0: No Flash Memory
2: 2Mbit Flash
4: 4Mbit Flash
8: 8Mbit Flash
6: 16Mbit Flash
3: 32Mbit Flash

6 Solder-Reflow Condition

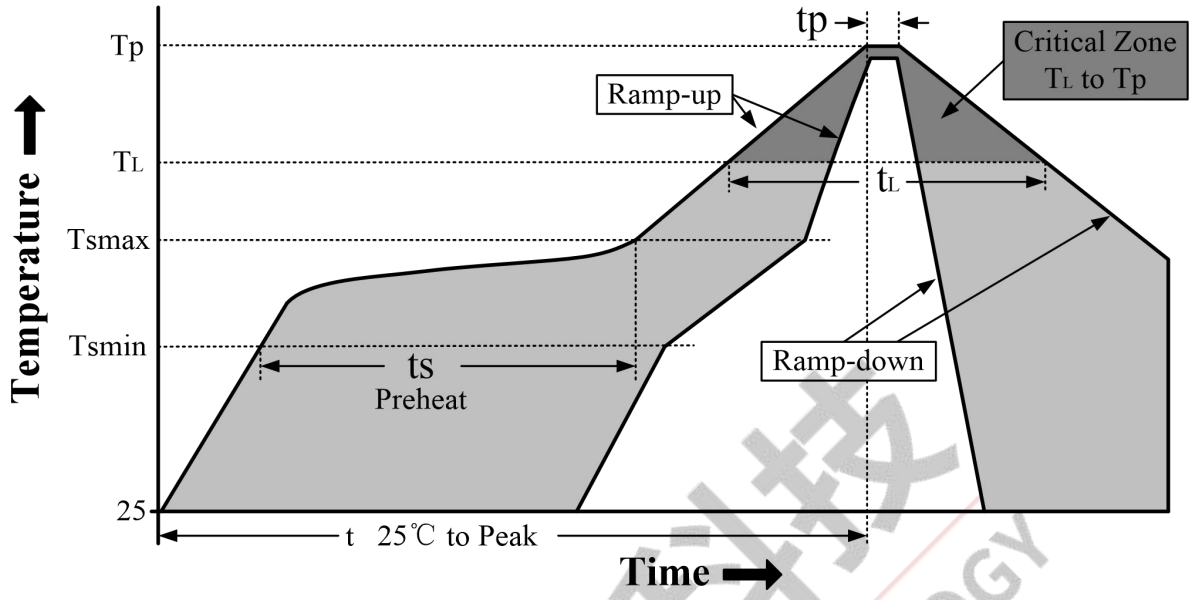


Figure 6-1 Classification Reflow Profile

Classification Profiles **Table 6-1**

Profile Feature		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Preheat/ Soak	Temperature Min (T_{smin})	100 ℃	150 ℃
	Temperature Max (T_{smax})	150 ℃	200 ℃
	Time (ts) from (T_{smin} to T_{smax})	60-120 seconds	60-180 seconds
Average ramp-up rate (T_{smax} to T_p)		3 ℃/second max	3 ℃/second max
Liquidous temperature (T_L) Time (t_L) maintained above T_L		183 ℃ 60-150 seconds	217 ℃ 60-150 seconds
Peak package body temperature (T_p)		See Table 6-2.	See Table 6-3.
Time within 5°C of actual Peak Temperature (tp)		10-30 seconds	20-40 seconds
Ramp-down rate (T_p to T_L)		6 ℃/second max.	6 ℃/second max.
Time 25 ℃ to peak temperature		6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5℃ of actual peak temperature (tp) specified for the reflow profiles is a “supplier” minimum and “user” maximum.

SnPb - Classification Temperature **Table 6-2**

Package Thickness	Volume mm^3 < 350	Volume mm^3 ≥ 350
<2.5 mm	240 +0/-5 ℃	225 +0/-5 ℃
≥ 2.5 mm	225 +0/-5 ℃	225 +0/-5 ℃

Pb-free - Classification Temperature **Table 6-3**

Package Thickness	Volume mm^3 < 350	Volume mm^3 350 - 2000	Volume mm^3 > 2000
< 1.6mm	260 ℃	260 ℃	260 ℃
1.6 mm - 2.5mm	260 ℃	250 ℃	245 ℃
> 2.5mm	250 ℃	245 ℃	245 ℃

7 Revision History

Date	Revision	Description
2022.09.16	V1.0	Initial Release.
2022.11.28	V1.1	Update Pin Definition. Update VPWR,VBAT range. Update DAC,ADC Test Conditions.
2023.03.22	V1.2	Features modification